

## Product Preview

# 256K Asynchronous Secondary Cache Module for Pentium™

The MCM64AF32 is designed to provide 256K of asynchronous L2 cache for the Pentium microprocessor in conjunction with Intel's Triton chip set. The module is configured as 32K x 64 bits in a 160 pin card edge connector. The module uses eight Motorola 3.3 V 32K x 8 FSRAMs for the cache memory, one Motorola 5 V 32K x 8 FSRAM for the tag RAM, and an upper order address latch.

Eight write enables are provided for byte write control.

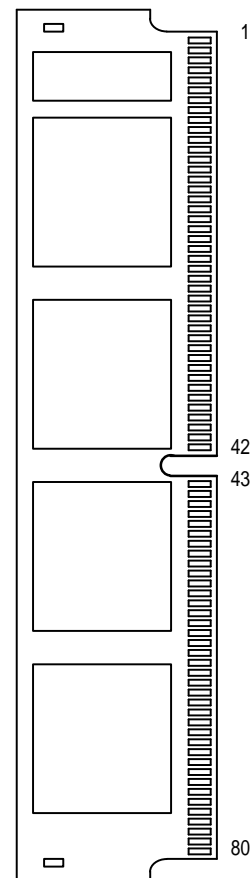
PD0-PD4 identify density and functionality.

This cache module is plug and pin compatible with the other members of Motorola's Triton chip set module family, the MCM72JG32SG66 (a 256K byte pipelined BurstRAM module) and the MCM72JG64SG66 (a 512K byte pipelined BurstRAM module).

- Low-Cost Asynchronous Solution for Triton Chip Set
- All Cache Data Inputs and Outputs are LVTTTL (3.3 V I/O) Compatible
- All Tag I/Os are TTL Compatible
- Byte Write Capability
- Fast SRAM Access Times: 15 ns for Data RAMs and Tag RAM
- Decoupling Capacitors for each Fast Static RAM and Logic Device
- High Quality Multi-Layer FR4 PWB With Separate Power and Ground Planes
- 160 Pin Card Edge Module
- Burndy Connector, Part Number: CELP2X80SC3Z48

## MCM64AF32

160-LEAD  
CARD EDGE  
CASE TBD\*  
TOP VIEW



\* SEE BACK PAGE FOR PRELIMINARY  
CASE OUTLINE.

BurstRAM is a trademark of Motorola.  
Pentium is a trademark of Intel Corp.

This document contains information on a product under development. Motorola reserves the right to change or discontinue this product without notice.

**PIN ASSIGNMENT**  
**160-LEAD CARD EDGE MODULE**  
**TOP VIEW**

**PRESENCE DETECT TABLE**

Cache Size and Functionality	Module	PD4	PD3	PD2	PD1	PD0
256KB Async	MCM64AF32	V <sub>SS</sub>	NC	V <sub>SS</sub>	V <sub>SS</sub>	NC
512KB Async	—	V <sub>SS</sub>	V <sub>SS</sub>	NC	V <sub>SS</sub>	NC
256K Burst	—	V <sub>SS</sub>	NC	V <sub>SS</sub>	NC	V <sub>SS</sub>
256K Pipe Burst	MCM72JG32	V <sub>SS</sub>	NC	V <sub>SS</sub>	NC	NC
512K Burst	—	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	V <sub>SS</sub>
512K Pipe Burst	MCM72JG64	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	NC
512K 2-Bank Burst	—	V <sub>SS</sub>	V <sub>SS</sub>	NC	V <sub>SS</sub>	V <sub>SS</sub>

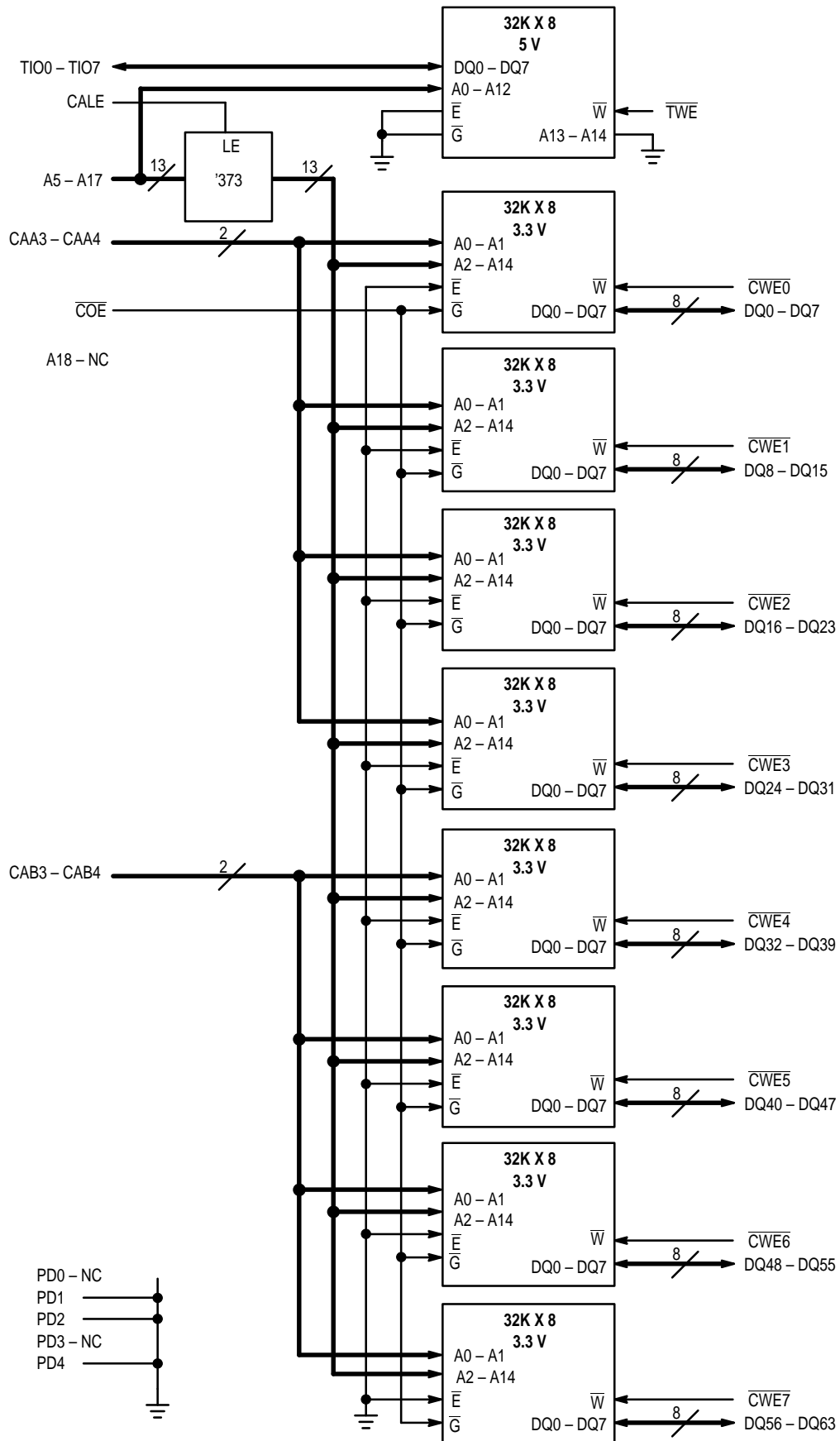
PIN NAMES	
TIO0 – TIO7	Tag RAM I/O
TWE	Tag Write Enable
CALE	Address Latch Enable
A5 – A17	Address Inputs
CWE0 – CWE7	Cache Write Enable
CAA3 – CAA4	Cache Address A
CAB3 – CAB4	Cache Address B
COE	Cache Output Enable
DQ0 – DQ63	Data Input/Output
PD0 – PD4	Presence Detect
V <sub>CC3</sub>	+ 3.3 V Power Supply
V <sub>CC5</sub>	+ 5.0 V Power Supply
V <sub>SS</sub>	Ground
NC	No Connection

For proper operation of the device, V<sub>SS</sub> must be connected to ground.

NOTE: Signals in parentheses indicate pin designations for burstable members of the Triton chip set module family.

V <sub>SS</sub>	81	1	V <sub>SS</sub>
TIO1	82	2	TIO0
TIO7	83	3	TIO2
TIO5	84	4	TIO6
TIO3	85	5	TIO4
(RSVD) NC	86	6	NC (RSVD)
V <sub>CC5</sub>	87	7	V <sub>CC3</sub>
(RSVD) NC	88	8	TWE
(CADV) CAA4	89	9	CAA3 (CADS)
V <sub>SS</sub>	90	10	V <sub>SS</sub>
COE	91	11	CWE4
CWE5	92	12	CWE6
CWE7	93	13	CWE0
CWE1	94	14	CWE2
V <sub>CC5</sub>	95	15	V <sub>CC3</sub>
CWE3	96	16	CAB4 (CCS)
CAB3	97	17	NC (GWE)
CALE	98	18	NC (BWE)
V <sub>SS</sub>	99	19	V <sub>SS</sub>
(RSVD) NC	100	20	NC (A3)
(A4) NC	101	21	A7
A6	102	22	A5
A8	103	23	A11
A10	104	24	A16
V <sub>CC5</sub>	105	25	V <sub>CC3</sub>
A17	106	26	NC (A18)
V <sub>SS</sub>	107	27	V <sub>SS</sub>
A9	108	28	A12
A14	109	29	A13
A15	110	30	NC (ADSP)
(RSVD) NC	111	31	NC (CS/ECS1)
PD0	112	32	NC (ECS2)
PD2	113	33	PD1
PD4	114	34	PD3
V <sub>SS</sub>	115	35	V <sub>SS</sub>
(CLK0) NC	116	36	NC (CLK1)
V <sub>SS</sub>	117	37	V <sub>SS</sub>
DQ63	118	38	DQ62
V <sub>CC5</sub>	119	39	V <sub>CC3</sub>
DQ61	120	40	DQ60
DQ59	121	41	DQ58
DQ57	122	42	DQ56
V <sub>SS</sub>	123	43	V <sub>SS</sub>
DQ55	124	44	DQ54
DQ53	125	45	DQ52
DQ51	126	46	DQ50
DQ49	127	47	DQ48
V <sub>SS</sub>	128	48	V <sub>SS</sub>
DQ47	129	49	DQ46
DQ45	130	50	DQ44
DQ43	131	51	DQ42
V <sub>CC5</sub>	132	52	V <sub>CC3</sub>
DQ41	133	53	DQ40
DQ39	134	54	DQ38
DQ37	135	55	DQ36
V <sub>SS</sub>	136	56	V <sub>SS</sub>
DQ35	137	57	DQ34
DQ33	138	58	DQ32
DQ31	139	59	DQ30
V <sub>CC5</sub>	140	60	V <sub>CC3</sub>
DQ29	141	61	DQ28
DQ27	142	62	DQ26
DQ25	143	63	DQ24
V <sub>SS</sub>	144	64	V <sub>SS</sub>
DQ23	145	65	DQ22
DQ21	146	66	DQ20
DQ19	147	67	DQ18
V <sub>CC5</sub>	148	68	V <sub>CC3</sub>
DQ17	149	69	DQ16
DQ15	150	70	DQ14
DQ13	151	71	DQ12
V <sub>SS</sub>	152	72	V <sub>SS</sub>
DQ11	153	73	DQ10
DQ9	154	74	DQ8
DQ7	155	75	DQ6
V <sub>CC5</sub>	156	76	V <sub>CC3</sub>
DQ5	157	77	DQ4
DQ3	158	78	DQ2
DQ1	159	79	DQ0
V <sub>SS</sub>	160	80	V <sub>SS</sub>

### MCM64AF32 MODULE BLOCK DIAGRAM



## PIN DESCRIPTIONS

160-Lead Card Edge Pin Locations	Symbol	Type	Description
21, 22, 23, 24, 28, 29, 102, 103, 104, 106, 108, 109, 110	A5 – A17	Input	Address Inputs: These inputs are latched into data RAMs and must meet setup and hold times. The tag RAM addresses are not latched. (See Block Diagram).
9, 89	CAA3, CAA4	Input	Cache Address A: Low order address inputs for bursting. Not latched.
16, 97	CAB3, CAB4	Input	Cache Address B: Low order address inputs for bursting. Not latched.
98	CALE	Input	Address Latch Enable: Active low signal latches A5 – A17.
11, 12, 13, 14, 92, 93, 94, 96	$\overline{\text{CWE0}} - \overline{\text{CWE7}}$	Input	Cache Data Write Enable: Active low write signal for data RAMs.
8	$\overline{\text{TWE}}$	Input	Tag Write Enable: Active low write signal for tag RAMs.
—	$\overline{\text{CS}}$	Input	Chip Select: Active low chip enable for tag and data RAMs. Not used.
91	$\overline{\text{COE}}$	Input	Cache Output Enable: Asynchronous active low output enable for data RAMs.
38, 40, 41, 42, 44, 45, 46, 47, 49, 50, 51, 53, 54, 55, 57, 58, 59, 61, 62, 63, 65, 66, 67, 69, 70, 71, 73, 74, 75, 77, 78, 79, 118, 120, 121, 122, 124, 125, 126, 127, 129, 130, 131, 133, 134, 135, 137, 138, 139, 141, 142, 143, 145, 146, 147, 149, 150, 151, 153, 154, 155, 157, 158, 159	DQ0 – DQ63	I/O	Data I/O
2, 3, 4, 5, 82, 83, 84, 85	TIO0 – TIO7	I/O	Tag RAM I/O: Drives data out during tag compare cycles. Stores data to tag RAM during tag WRITE cycles.
33, 34, 112, 113, 114	PD0 – PD4		Presence Detect: See Presence Detect Table.
7, 15, 25, 39, 52, 60, 68, 76	VCC3	Supply	Power Supply: 3.3 V ± 5%.
87, 95, 105, 119, 132, 140, 148, 156	VCC5	Supply	Power Supply: 5.0 V ± 5%.
1, 10, 19, 27, 35, 37, 43, 48, 56, 64, 72, 80, 81, 90, 99, 107, 115, 117, 123, 128, 136, 144, 152, 160	VSS	Supply	Ground
6, 17, 18, 20, 26, 30, 31, 32, 36, 86, 88, 100, 101, 111, 116	NC	—	No Connection: There is no connection to the module.

**TRUTH TABLE FOR TAG AND DATA RAMs (X = Don't Care)**

COE	CWE	Mode	V <sub>CC</sub> Current	Output	Cycle
H	H	Output Disabled	I <sub>CCA</sub>	High-Z	—
L	H	Read	I <sub>CCA</sub>	D <sub>out</sub>	Read Cycle
X	L	Write	I <sub>CCA</sub>	High-Z	Write Cycle

**ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Power Supply Voltage for Tag for Data	V <sub>CC5</sub> V <sub>CC3</sub>	- 0.5 to + 7.0 - 0.5 to + 5.0	V
Voltage Relative to V <sub>SS</sub>	V <sub>in</sub> , V <sub>out</sub>	- 0.5 to V <sub>CC</sub> + 0.5*	V
Output Current (per I/O)	I <sub>out</sub>	± 20	mA
Temperature Under Bias	T <sub>bias</sub>	- 10 to + 85	°C
Operating Temperature	T <sub>A</sub>	0 to + 70	°C
Storage Temperature – Plastic	T <sub>stg</sub>	- 55 to + 125	°C

\* For data RAMs, V<sub>CC</sub> + 2.0 V ac to V<sub>SS</sub> - 2.0 V ac (pulse width ≤ 20 ns).

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

**DC OPERATING CONDITIONS AND CHARACTERISTICS**

(V<sub>CC3</sub> = 3.3 V ± 5%, V<sub>CC5</sub> = 5.0 V ± 5%, T<sub>A</sub> = 0 to + 70°C, Unless Otherwise Noted)

**RECOMMENDED OPERATING CONDITIONS (Voltages Referenced to V<sub>SS</sub> = 0 V)**

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage (Operating Voltage Range) Tag RAM Data RAM and Latch	V <sub>CC</sub>	4.75 3.135	5.0 3.3	5.25 3.465	V
Input High Voltage	V <sub>IH</sub>	2.2	—	V <sub>CC</sub> + 0.3*	V
Input Low Voltage	V <sub>IL</sub>	- 0.5**	0.0	0.8	V

\* For Tag, V<sub>IH</sub> (max) = V<sub>CC</sub> + 0.3 V dc; V<sub>IH</sub> (max) = V<sub>CC</sub> + 2.0 V ac (pulse width ≤ 20 ns).

For Data, V<sub>IH</sub> (max) = V<sub>CC</sub> + 0.3 V dc; V<sub>IH</sub> (max) = V<sub>CC</sub> + 2.0 V ac (pulse width ≤ 10% t<sub>AVAV</sub> (min)).

\*\* For Tag, V<sub>IL</sub> (min) = - 0.5 V dc; V<sub>IL</sub> (min) = - 2.0 V ac (pulse width ≤ 20 ns).

For Data, V<sub>IL</sub> (min) = - 0.5 V dc; V<sub>IL</sub> (min) = - 2.0 V ac (pulse width ≤ 10% t<sub>AVAV</sub> (min)).

**DC CHARACTERISTICS**

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V <sub>in</sub> = 0 to V <sub>CC</sub> )	I <sub>lkg(I)</sub>	—	± 2	μA
Output Leakage Current (COE = V <sub>IH</sub> , V <sub>out</sub> = 0 to V <sub>CC</sub> )	I <sub>lkg(O)</sub>	—	± 2	μA
TTL Output Low Voltage (I <sub>OL</sub> = + 8.0 mA)	V <sub>OL</sub>	—	0.4	V
TTL Output High Voltage (I <sub>OH</sub> = - 4.0 mA)	V <sub>OH</sub>	2.4	—	V
CMOS Output Low Voltage (I <sub>OL</sub> = 100 μA)	V <sub>OL2</sub>	—	0.1	V
CMOS Output High Voltage (I <sub>OH</sub> = - 100 μA)	V <sub>OH2</sub>	V <sub>CC</sub> - 0.1	—	V

NOTE: NOTE: Good decoupling of the local power supply should always be used.

**POWER SUPPLY CURRENTS**

Parameter	Symbol	Max	Unit
AC Active Supply Current (I <sub>out</sub> = 0 mA, V <sub>CC</sub> = Max, f = f <sub>max</sub> )	I <sub>CCA</sub>	780	mA

**CAPACITANCE** (f = 1.0 MHz, dV = 3.0 V, T<sub>A</sub> = 25°C, Periodically Sampled Rather Than 100% Tested)

Parameter	Symbol	Max	Unit
Input Capacitance ( $\overline{TWE}$ , CALE, $\overline{CWE0 - CWE7}$ (A5 – A17) (CAA3, CAA4, CAB3, CAB4) ( $\overline{COE}$ )	C <sub>in</sub>	8 14 26 50	pF
Input/Output Capacitance (DQ0 – DQ63) (TIO0 – TIO7)	C <sub>I/O</sub>	8 10	pF

**DATA RAMs AC OPERATING CONDITIONS AND CHARACTERISTICS**

(V<sub>CC</sub> = 3.3 V ± 5%, T<sub>A</sub> = 0 to + 70°C, Unless Otherwise Noted)

Input Timing Measurement Reference Level ..... 1.5 V      Output Timing Measurement Reference Level ..... 1.5 V  
 Input Pulse Levels ..... 0 to 3.0 V      Output Load ..... Figure 1A Unless Otherwise Noted  
 Input Rise/Fall Time ..... 3 ns

**DATA RAMs READ CYCLE** (See Note 1)

Parameter	Symbol	-15		Unit	Notes
		Min	Max		
Read Cycle Time	t <sub>AVAV</sub>	15	—	ns	2
Address Access Time (CAAx, CABx)	t <sub>AVQV</sub>	—	15	ns	
Latched Address Access Time (A5 – A17)	t <sub>LAVQV</sub>	—	22	ns	
Latched Address to CALE Low Setup Time	t <sub>AVCALL</sub>	4	—	ns	
Latched Address to CALE Low Hold Time	t <sub>CALAX</sub>	3	—	ns	
Enable Access Time	t <sub>ELQV</sub>	—	15	ns	3
Output Enable Access Time	t <sub>GLQV</sub>	—	8	ns	
Output Hold from Address Change	t <sub>AXQX</sub>	4	—	ns	6
Enable Low to Output Active	t <sub>ELQX</sub>	4	—	ns	4, 5, 6
Enable High to Output High-Z	t <sub>EHQZ</sub>	0	8	ns	4, 5, 6
Output Enable Low to Output Active	t <sub>GLQX</sub>	0	—	ns	4, 5, 6
Output Enable High to Output High-Z	t <sub>GHQZ</sub>	0	7	ns	4, 5, 6
Power Up Time	t <sub>ELICCH</sub>	0	—	ns	
Power Down Time	t <sub>EHICCL</sub>	—	15	ns	

NOTES:

1.  $\overline{CWE}$  is high for read cycle.
2. All timings are referenced from the last valid address to the first address transition.
3. Addresses valid prior to or coincident with  $\overline{CS}$  going low.
4. At any given voltage and temperature, t<sub>GHQZ</sub> (max) is less than t<sub>GLQX</sub> (min), both for a given device and from device to device.
5. Transition is measured ± 500 mV from steady-state voltage with load of Figure 1B.
6. This parameter is sampled and not 100% tested.
7. Device is continuously selected ( $\overline{COE} = V_{IL}$ ).

**AC TEST LOADS**

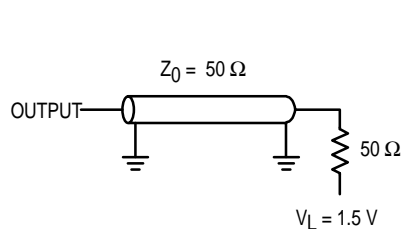


Figure 1A

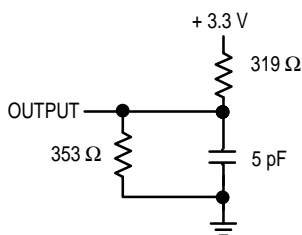
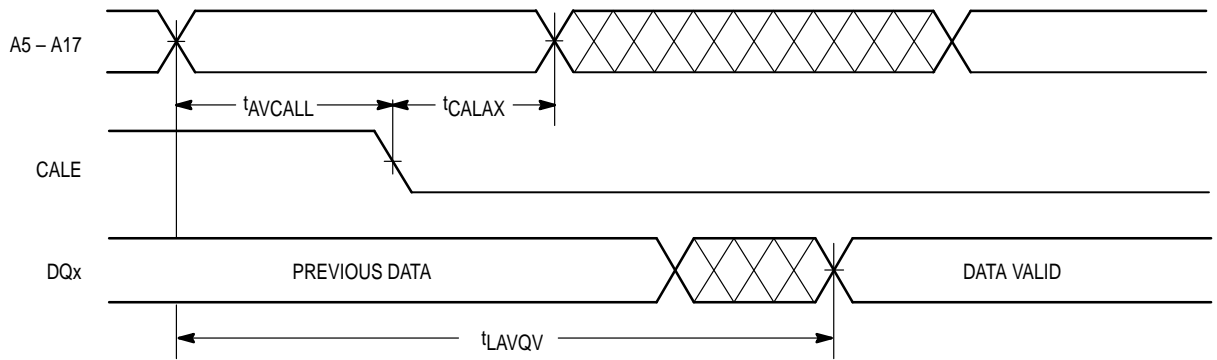


Figure 1B

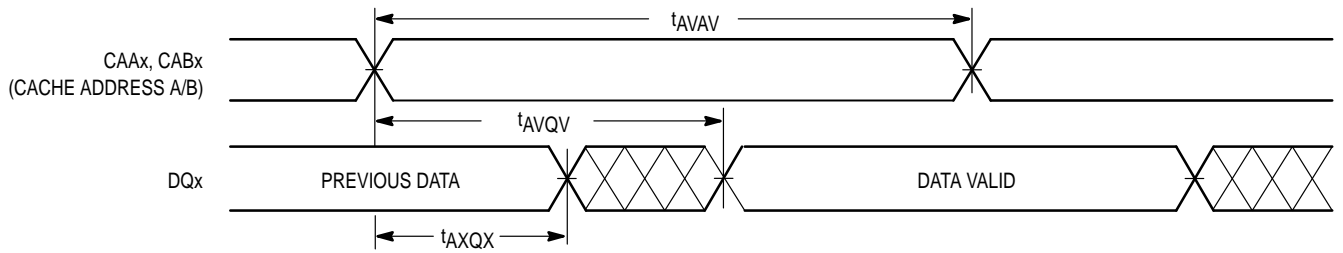
**TIMING LIMITS**

The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

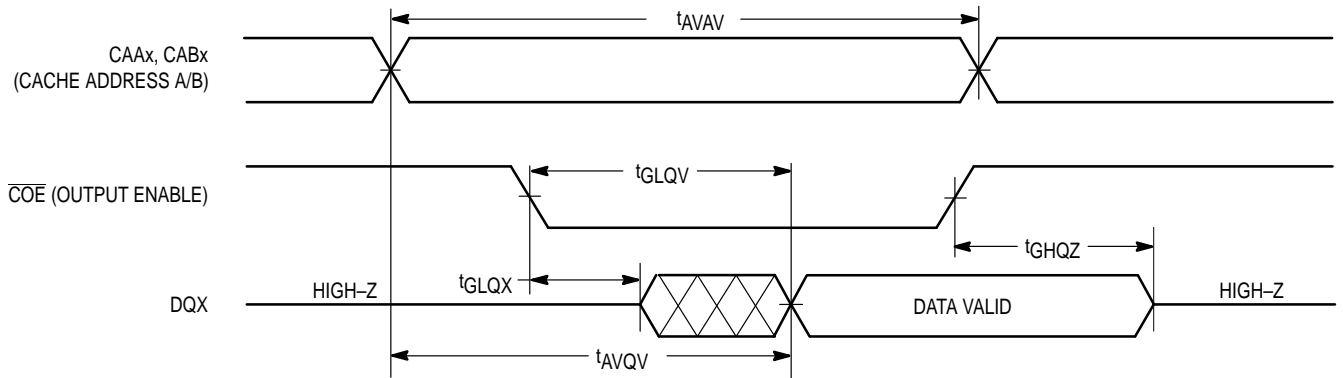
**DATA RAMs FIRST ACCESS READ CYCLE (See Note 7)**



**DATA RAMs BURST ACCESS READ CYCLE (CALE  $\leq V_{IL}$ ) (See Note 7)**



**DATA RAMs READ CYCLE 3 (CALE  $\leq V_{IL}$ ) (See Note 3)**



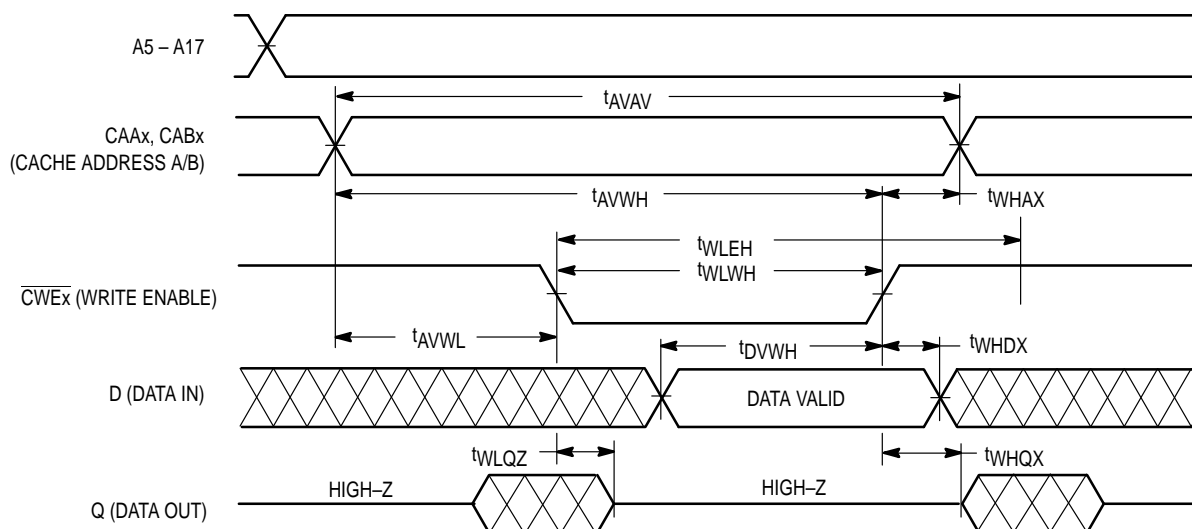
**DATA RAMs WRITE CYCLE** ( $\overline{CWE}$  Controlled, See Notes 1 and 2)

Parameter	Symbol	-15		Unit	Notes
		Min	Max		
Write Cycle Time	$t_{AVAV}$	15	—	ns	3
Address Setup Time	$t_{AVWL}$	0	—	ns	
Address Valid to End of Write	$t_{AVWH}$	12	—	ns	
Write Pulse Width	$t_{WLWH}$ , $t_{WLEH}$	12	—	ns	
Write Pulse Width, $\overline{COE}$ High	$t_{WLWH}$ , $t_{WLEH}$	10	—	ns	4
Data Valid to End of Write	$t_{DVWH}$	7	—	ns	
Data Hold Time	$t_{WHDX}$	0	—	ns	
Write Low to Output High-Z	$t_{WLQZ}$	0	7	ns	5, 6, 7
Write High to Output Active	$t_{WHQX}$	4	—	ns	5, 6, 7
Write Recovery Time	$t_{WHAX}$	0	—	ns	

NOTES:

1. A write occurs when  $\overline{CWE}$  low.
2. If  $\overline{COE}$  goes low coincident with or after  $\overline{CWE}$  goes low, the output will remain in a high impedance state.
3. All timings are referenced from the last valid address to the first address transition.
4. If  $\overline{COE} \geq V_{IH}$ , the output will remain in a high impedance state.
5. At any given voltage and temperature,  $t_{WLQZ}$  max is less than  $t_{WHQX}$  min, both for a given device and from device to device.
6. Transition is measured  $\pm 500$  mV from steady-state voltage with load of Figure 1B.
7. This parameter is sampled and not 100% tested.

**DATA RAMs WRITE CYCLE** ( $CALE \geq V_{IH}$ ) ( $\overline{CWE}$  Controlled, See Notes 1 and 2)





## TAG RAM AC OPERATING CONDITIONS AND CHARACTERISTICS

( $V_{CC} = 5.0\text{ V} \pm 5\%$ ,  $T_A = 0\text{ to } +70^\circ\text{C}$ , Unless Otherwise Noted)

Input Timing Measurement Reference Level ..... 1.5 V  
 Input Pulse Levels ..... 0 to 3.0 V  
 Input Rise/Fall Time ..... 3 ns

Output Timing Measurement Reference Level ..... 1.5 V  
 Output Load ..... Figure 1A Unless Otherwise Noted

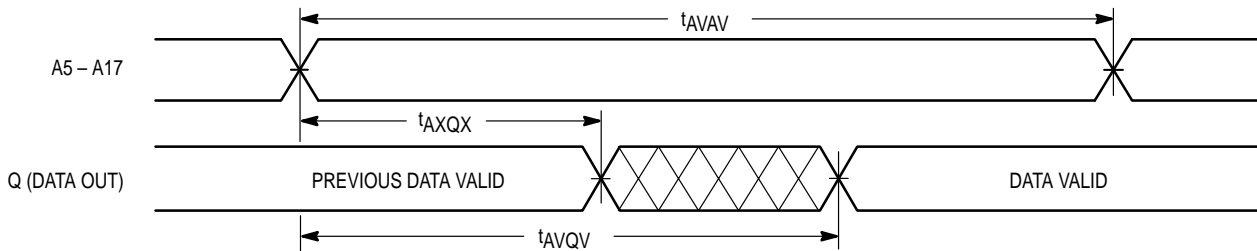
### TAG RAM READ CYCLE (See Notes 1 and 5)

Parameter	Symbol	- 15		Unit	Notes
		Min	Max		
Read Cycle Time	$t_{AVAV}$	15	—	ns	2
Address Access Time	$t_{AVQV}$	—	15	ns	
Output Hold from Address Change	$t_{AXQX}$	4	—	ns	3, 4

**NOTES:**

1.  $\overline{CWE}$  is high for read cycle.
2. All timings are referenced from the last valid address to the first address transition.
3. Transition is measured  $\pm 500\text{ mV}$  from steady-state voltage with load of Figure 1B.
4. This parameter is sampled and not 100% tested.
5. Device is continuously selected ( $\overline{COE} = V_{IL}$ ).

### TAG RAM READ CYCLE (See Note 5)



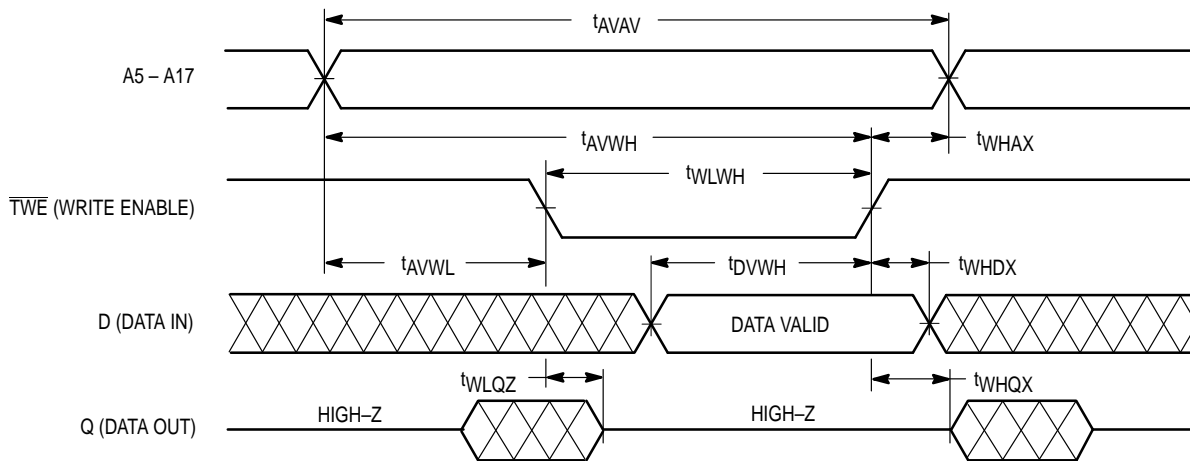
**TAG RAM WRITE CYCLE** (See Notes 1 and 2)

Parameter	Symbol	- 15		Unit	Notes
		Min	Max		
Write Cycle Time	$t_{AVAV}$	15	—	ns	3
Address Setup Time	$t_{AVWL}$	0	—	ns	
Address Valid to End of Write	$t_{AVWH}$	12	—	ns	
Data Valid to End of Write	$t_{DVWH}$	7	—	ns	
Data Hold Time	$t_{WHDX}$	0	—	ns	
Write Low to Output High-Z	$t_{WLQZ}$	0	7	ns	5, 6, 7
Write High to Output Active	$t_{WHQX}$	4	—	ns	5, 6, 7
Write Recovery Time	$t_{WHAX}$	0	—	ns	

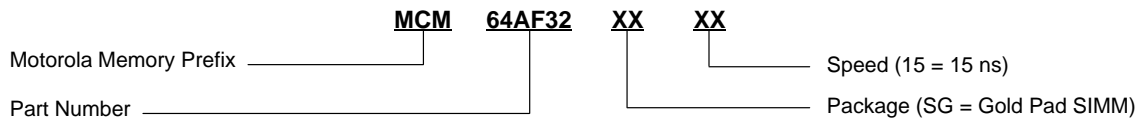
**NOTES:**

1. A write occurs when  $\overline{CWE}$  is low.
2. If  $\overline{COE}$  goes low coincident with or after  $\overline{CWE}$  goes low, the output will remain in a high impedance state.
3. All timings are referenced from the last valid address to the first address transition.
4. If  $\overline{COE} \geq V_{IH}$ , the output will remain in a high impedance state.
5. At any given voltage and temperature,  $t_{WLQZ}$  (max) is less than  $t_{WHQX}$  (min), both for a given device and from device to device.
6. Transition is measured  $\pm 500$  mV from steady-state voltage with load of Figure 1B.
7. This parameter is sampled and not 100% tested.

**TAG RAM WRITE CYCLE** (See Notes 1 and 2)

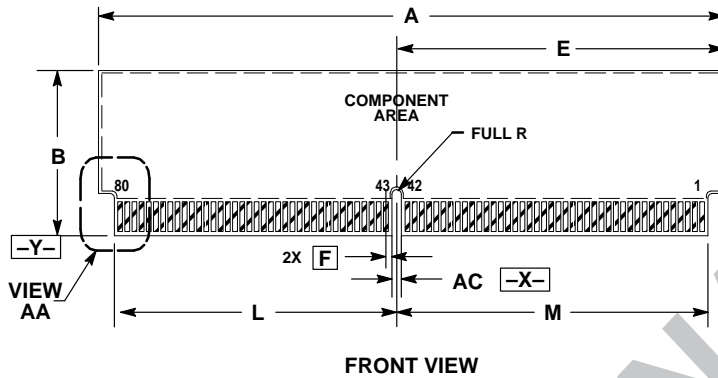


**ORDERING INFORMATION**  
(Order by Full Part Number)

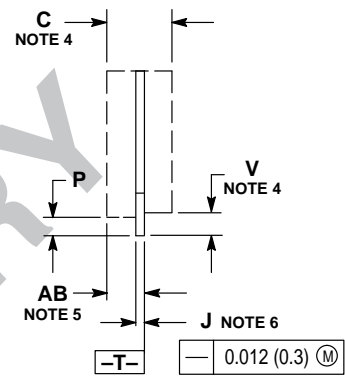


Full Part Number — MCM64AF32SG15

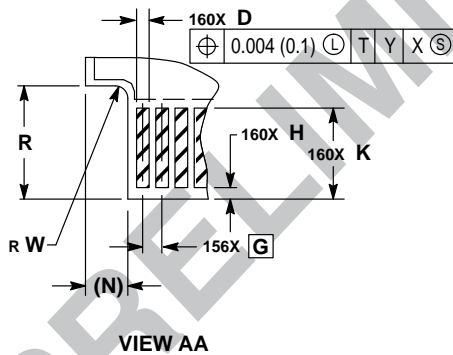
**PACKAGE DIMENSIONS**  
**CARD EDGE MODULE**  
**160-LEAD**  
**CASE TBD**



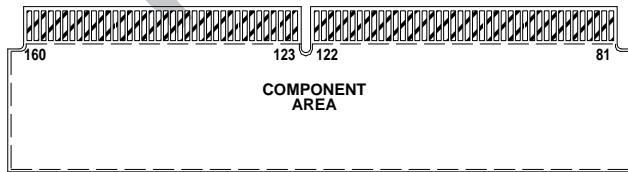
**FRONT VIEW**



**SIDE VIEW**




**VIEW AA**



**BACK VIEW**

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
  4. DIMENSIONS C AND V DEFINE A DOUBLE-SIDED MODULE.
  5. DIMENSION AB DEFINES OPTIONAL SINGLE-SIDED MODULE.
  6. STRAIGHTNESS CALLOUT APPLIES TO TAB AREA ONLY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	4.330	4.350	109.98	110.49
B	1.290	1.310	32.77	33.27
C	—	0.454	—	11.53
D	0.033	0.037	0.84	0.94
E	2.265	2.275	57.53	57.79
F	0.075 BSC		1.91 BSC	
G	0.050 BSC		1.27 BSC	
H	—	0.030	—	0.51
J	0.055	0.069	1.40	1.75
K	0.210	—	5.33	—
L	1.955	1.965	49.66	49.91
M	2.155	2.165	54.74	54.99
N	0.110 REF		2.79 REF	
P	0.125	—	3.18	—
R	0.285	0.305	7.24	7.75
V	0.157	—	3.99	—
W	0.040	0.060	1.02	1.52
AB	—	0.262	—	6.66
AC	0.072	0.076	1.83	1.93

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and  are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

**Literature Distribution Centers:**

USA/EUROPE: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036.

JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141, Japan.

ASIA PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.



MCM64AF32/D

